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Gp/2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Application Ser. No. 09/768,372 : Art Unit 2827

Filed 1/23/01 : Ext. K. Cuneo

Inventors Blackshear et.al

Atty Dkt No YOR919980001US2

For: STRESS ACCOMMODATION IN ELECTRONIC DEVICE  
INTERCONNECT TECHNOLOGY FOR MILLIMETER CONTACT LOCATIONS

Amndt

Crew/Dwgs

Jmc/millor

11/6/02

Response to 5/9/02 Office Action

Assistant Commissioner for Patents  
U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In response to the 5/9/02 office action kindly amend this application as follows.

In the claims:

Claim 1 is to be amended by erasing on line 12 the cross hatched word "operable" and replacing it with the underlined expression - so positioned - as follows.

1. 1. In an array of conductive joints between signal pads on a surface of an integrated circuit
- 2 member of a material having a first thermal responsiveness and corresponding
- 3 contacts on an aligned wiring support member of a material having a second thermal
- 4 responsiveness,
- 5 the improvement comprising:
- 6 an interface having first and second portions,
- 7 said first portion of said interface containing an array of elongated conductive joint
- 8 members each having a contacting area made up of a length contacting dimension and
- 9 a width contacting dimension and with said length contacting dimension being longer

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